



2:214

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Egon Mergenthaler et al. Art Unit : 2814  
Serial No. : 10/037,213 Examiner : Dana Farahani  
Filed : November 9, 2001  
Title : TIEDOWNS CONNECTED TO KERF REGIONS AND EDGE SEALS

Commissioner for Patents  
Washington, D.C. 20231

AMENDMENT

In response to the Office Action dated November 18, 2002, please amend the above-identified application as follows:

IN THE CLAIMS:

Please amend claims 1, 7, 10 and 17 as follows:

--1. (Amended) A tiedown structure, comprising:  
a semiconductor substrate having a chip formed thereon;  
a kerf region proximate the chip; and  
a conductive connector forming an electrical connection between the chip and the kerf region.

CERTIFICATE OF MAILING BY FIRST CLASS MAIL

I hereby certify under 37 CFR §1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated below and is addressed to the Commissioner for Patents, Washington, D.C. 20231.

Date of Deposit

Signature

Stefanie Dion  
Typed or Printed Name of Person Signing Certificate